	Type	Hits	Search Text	DBs	Time Stamp	Comments
1	BRS	41	set$4 with up with (IC$1 or integrated adj circuit$1) with chip$1 with test$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 11:39	
2	BRS	10	set$4 with up with (IC$1 or integrated adj circuit$1) with chip$1 with test$3 and (i/o or input/output)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 11:41	
3	BRS	6	set$4 with up with (IC$1 or integrated adj circuit$1) with chip$1 with test$3 and (i/o or input/output) with terminal$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 15:02	
4	BRS	1	set$4 with up with (IC$1 or integrated adj circuit$1) with chip$1 with test$3 and (i/o or input/output) and terminal$1 with shar$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 11:45	
5	BRS	6	test$3 with first with (IC$1 or integrated adj circuit$1) with chip$1 and (i/o or input/output) and terminal$1 with shar$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 12:55	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
6	BRS	105	(ICs or integrated adj circuits) with combin$6 with package	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 13:02	
7	BRS	101	multiple with (IC$1 or integrated adj circuit$1) with combin$6 with package	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 13:03	
8	BRS	3	multiple with (IC$1 or integrated adj circuit$1) with combin$6 with package with terminal$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 13:04	
9	BRS	0	test$3 with multiple with (IC$1 or integrated adj circuit$1) with combin$6 with package with terminal$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 13:04	
10	BRS	7	test$3 with (IC$1 or integrated adj circuit$1) with combin$6 with package with terminal$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 13:06	
11	BRS	35	test$3 with (IC$1 or integrated adj circuit$1) with shar$3 with terminal$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 13:22	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
12	BRS	3	test$3 with first with (IC$1 or integrated adj circuit$1) with shar$3 with terminal$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 13:09	
13	BRS	2	test$3 with first adj (IC$1 or integrated adj circuit$1) with shar$3 with terminal$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 13:09	
14	BRS	2	test$3 with (integrated adj circuit$1 ir IC$1 or semiconductor$1 or wafter$1) and first adj (IC$1 or integrated adj circuit$1) with shar$3 with terminal$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 13:10	
15	BRS	2	test$3 with (integrated adj circuit$1 ir IC$1 or semiconductor$1 or wafter$1) and first adj (integrated adj circuit$1 ir IC$1 or semiconductor$1 or wafter$1) with shar$3 with terminal$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 13:10	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
16	BRS	303	test$3 with (integrated adj circuit$1 ir IC$1 or semiconductor$1 or wafter$1) and first adj (integrated adj circuit$1 ir IC$1 or semiconductor$1 or wafter$1) with terminal$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 13:10	
17	BRS	54	test$3 with (integrated adj circuit$1 ir IC$1 or semiconductor$1 or wafter$1) and first adj (integrated adj circuit$1 ir IC$1 or semiconductor$1 or wafter$1) with terminal$1 with package$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 13:12	
18	BRS	2	test$3 with (integrated adj circuit$1 ir IC$1 or semiconductor$1 or wafter$1) and first adj (integrated adj circuit$1 ir IC$1 or semiconductor$1 or wafter$1) with terminal$1 with (combin$6 or shar$3) with package$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 13:12	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
19	BRS	57	test$3 with (integrated adj circuit$1 ir IC$1 or semiconductor$1 or wafter$1) and (integrated adj circuit$1 ir IC$1 or semiconductor$1 or wafter$1) with terminal$1 with (combin$6 or shar$3) with package$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 13:13	
20	BRS	12	test$3 with (integrated adj circuit$1 ir IC$1 or semiconductor$1 or wafter$1) and first with second with (integrated adj circuit$1 ir IC$1 or semiconductor$1 or wafter$1) with terminal$1 with (combin$6 or shar$3) with package$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 13:14	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
21	BRS	2	test$3 with (integrated adj circuit$1 ir IC$1 or semiconductor$1 or wafter$1) and first with second with (integrated adj circuit$1 ir IC$1 or semiconductor$1 or wafter$1) with terminal$1 with (combin$6 or share or sharing) with package$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 13:14	
22	BRS	45	test$3 with (integrated adj circuit$1 ir IC$1 or semiconductor$1 or wafter$1) and (integrated adj circuit$1 ir IC$1 or semiconductor$1 or wafter$1) with terminal$1 with (combin$6 or share or sharing) with package$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 13:17	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
23	BRS	15	test$3 with (integrated adj circuit$1 ir IC$1 or semiconductor$1 or wafter$1) and (integrated adj circuit$1 ir IC$1 or semiconductor$1 or wafter$1) with external with terminal$1 with (combin$6 or share or sharing) with package$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 13:17	
24	BRS	3737	test$3 with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1) and terminal$1 with pin$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 13:23	
25	BRS	963	test$3 with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1) with terminal$1 with pin$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 13:23	
26	BRS	167	test$3 with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1) with external$1 with terminal$1 with pin$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 13:23	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
27	BRS	41	test$3 with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1) with external$1 with terminal$1 with pin$1 with package$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 13:26	
28	BRS	5	test$3 with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1) with (chip$1 or component$1) with external$1 with terminal$1 with pin$1 with package$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 13:27	
29	BRS	81	test$3 with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1) with (chip$1 or component$1) and external$1 with terminal$1 with pin$1 with package$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 08:10	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
30	BRS	8	test$3 with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1) with (chip$1 or component$1) and external$1 with terminal$1 with pin$1 with package$1 and power$3 with down	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 13:30	
31	BRS	23	(combin$6 or share$1 or sharing) with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1) with (chip$1 or component$1) with external$1 with terminal$1 with package$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 13:32	
32	BRS	23	external$1 with terminal$1 with package$1 with (combin$6 or share$1 or sharing) with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1) with (chip$1 or component$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 13:37	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
33	BRS	0	external$1 with terminal$1 with package$1 with (combin$6 or share$1 or sharing) with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1) with (chip$1 or component$1) and power with (down or shutdown)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 13:37	
34	BRS	0	external$1 with terminal$1 with package$1 with (combin$6 or share$1 or sharing) with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1) with (chip$1 or component$1) and power with (down or shutdown or off)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 13:38	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
35	BRS	0	external$1 with terminal$1 with package$1 with (combin$6 or share$1 or sharing) with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1) with (chip$1 or component$1) and power$3 with (down or shutdown or off)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 13:38	
36	BRS	0	external$1 with terminal$1 with package$1 with (combin$6 or share$1 or sharing) with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1) with (chip$1 or component$1) and (electric$4 or power$3) with (down or shutdown or off)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 13:40	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
37	BRS	0	external$1 with terminal$1 with package$1 with (combin$6 or share$1 or sharing) with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1) with (chip$1 or component$1) and power-off	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 13:39	
38	BRS	2	external$1 with terminal$1 with package$1 with (combin$6 or share$1 or sharing) with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1) with (chip$1 or component$1) and (electric$4 or power$3) with (down or shutdown or off or isolat$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 13:41	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
39	BRS	4	external$1 with terminal$1 with package$1 with (combin$6 or share$1 or sharing) with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1) with (chip$1 or component$1) and (electric$4 or power$3) with (down or shutdown or off or isolat$3 or disconnect$3 or "not connected")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 13:45	
40	BRS	4	external$1 with terminal$1 with package$1 with (combin$6 or share$1 or sharing) with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1) with (chip$1 or component$1) and (electric$4 or power$3) with (down or shutdown or off or isolat$3 or dis-connect$3 or disconnect$3 or "not connected")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 13:45	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
41	BRS	1	terminal$1 with package$1 with (combin$6 or share$1 or sharing) with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1) with (chip$1 or component$1) same (electric$4 or power$3) with (down or shutdown or off or isolat$3 or dis-connect$3 or disconnect$3 or "not connected")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 13:46	
42	BRS	19	terminal$1 with package$1 with (combin$6 or share$1 or sharing) with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1) with (chip$1 or component$1) and (electric$4 or power$3) with (down or shutdown or off or isolat$3 or dis-connect$3 or disconnect$3 or "not connected")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 15:32	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
43	BRS	5	terminal$1 with package$1 with (combin$6 or share$1 or sharing) with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1) with (chip$1 or component$1) and (electric$4 or power$3) with (down or shutdown or off or isolat$3 or dis-connect$3 or disconnect$3 or "not connected") and test$3 with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1) with (chip$1 or component$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 13:52	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
44	BRS	1	terminal$1 with package$1 with (combin$6 or share$1 or sharing) with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1) with (chip$1 or component$1) and (electric$4 or power$3) with (down or shutdown or off or isolat$3 or dis-connect$3 or disconnect$3 or "not connected") and test$3 adj (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1) with (chip$1 or component$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 13:53	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
45	BRS	6	terminal$1 with package$1 with (bond$3 or combin$6 or share$1 or sharing) with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1) with (chip$1 or component$1) and (electric$4 or power$3) with (down or shutdown or off or isolat$3 or dis-connect$3 or disconnect$3 or "not connected") and test$3 adj (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1) with (chip$1 or component$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 14:28	
46	BRS	79	tri-stat$3 with (input/output or I/O) with (IC$1 or integrated with circuit$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 16:18	
47	BRS	4	tri-stat$3 with (input/output or I/O) with (IC$1 or integrated with circuit$1) and terminal$1 with package$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 15:30	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
48	BRS	6	tri-stat$3 with (input/output or I/O) with (IC$1 or integrated with circuit$1 or wafer$1 or semiconductor$1) with (chip$1 or component$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 14:10	
49	BRS	3	tri-stat$3 with (input/output or I/O) with (IC$1 or integrated with circuit$1 or wafer$1 or semiconductor$1) with (chip$1 or component$1) with test$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 14:21	
50	BRS	3	tri-stat$3 with (input/output or I/O) with (IC$1 or integrated with circuit$1 or wafer$1 or semiconductor$1) with (chip$1 or component$1) and operat$3 with test$3 with mode$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 14:23	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
51	BRS	0	terminal$1 with package$1 with (bond$3 or combin$6 or share$1 or sharing) with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1) with (chip$1 or component$1) and (electric$4 or power$3) with (down or shutdown or off or isolat$3 or dis-connect$3 or disconnect$3 or "not connected") and test$3 adj (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1) with (chip$1 or component$1) and (pre-charg$3 or pre adj charg$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 14:28	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
52	BRS	7	terminal$1 with package$1 with (combin$6 or share$1 or sharing) with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1) with (chip$1 or component$1) and (electric$4 or power$3) with (down or shutdown or off or isolat$3 or dis-connect$3 or disconnect$3 or "not connected") and memory	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 14:47	
53	BRS	1	test$3 with terminal$1 with package$1 with (combin$6 or share$1 or sharing) with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1) with (chip$1 or component$1) and (electric$4 or power$3) with (down or shutdown or off or isolat$3 or dis-connect$3 or disconnect$3 or "not connected") and memory	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 14:55	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
54	BRS	31486	702/108,117,118,120,,121,123.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 14:57	
55	BRS	727	714/733.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 16:20	
56	BRS	3802	365/201,208.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 15:03	
57	BRS	0	tri-stat$3 with (input/output or I/O) with driver$1 with (IC$1 or integrated with circuit$1) and terminal$1 with package$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 15:30	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
58	BRS	29	external with terminal$1 with (combin$6 or share$1 or sharing) with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1) with (chip$1 or component$1) and (electric$4 or power$3) with (down or shutdown or off or isolat$3 or dis-connect$3 or disconnect$3 or "not connected")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 15:56	
59	BRS	29	external with terminal$1 with (combin$6 or share$1 or sharing) with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1) with (chip$1 or component$1) and (electric$4 or power$3) with (down or shutdown or off or isolat$3 or dis-connect$3 or disconnect$3 or "not connected" or discoupled)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 15:59	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
60	BRS	2	tri-stat$3 with (input/output or I/O) with (IC$1 or integrated with circuit$1) and standby with current$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 16:24	
61	BRS	3739	714/724,725,733.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 16:20	
62	BRS	2811	326/38-41.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 16:20	
63	BRS	6	tri-stat$3 with (input/output or I/O) with (IC$1 or integrated with circuit$1 or wafer$1 or semiconductor$1 or chip$1) and standby with current$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/06 16:24	
64	BRS	225	test$3 with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1 or chip$1) and shar$3 with terminal$1 and memory with (set-up or setup or set adj up or condition$1 or state$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 08:13	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
65	BRS	28	test$3 with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1 or chip$1) and shar$3 with terminal$1 and memory with (set-up or setup or set adj up or condition$1 or state$1) and electric$4 with (shut-down or shutdown or shut adj down or isolat$3 or disconnect$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 08:16	
66	BRS	0	test$3 with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1 or chip$1) and shar$3 with terminal$1 and memory with tri-stat$3 and electric$4 with (shut-down or shutdown or shut adj down or isolat$3 or disconnect$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 08:17	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
67	BRS	11	test$3 with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1 or chip$1) and terminal$1 and memory with tri-stat$3 and electric$4 with (shut-down or shutdown or shut adj down or isolat$3 or disconnect$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 10:07	
68	BRS	1	test$3 with first with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1 or chip$1) and terminal$1 and memory and tri-stat$3 with second with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1 or chip$1) and electric$4 with (shut-down or shutdown or shut adj down or isolat$3 or disconnect$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 08:32	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
69	BRS	8	test$3 with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1 or chip$1) same tri-stat$3 with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1 or chip$1) and electric$4 with (shut-down or shutdown or shut adj down or isolat$3 or disconnect$3) and terminal$1 and memory	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 08:38	
70	BRS	6	test$3 with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1 or chip$1) and (isolat$3 or tri-stat$3) with driver$1 and (power$3 or electric$4) with (shut-down or shutdown or shut adj down or isolat$3 or disconnect$3) and shar$3 with terminal$1 and memory	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 08:53	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
71	BRS	8	test$3 with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1 or chip$1) and (isolat$3 or tri-stat$3) with drive$4 and (power$3 or electric$4) with (shut-down or shutdown or shut adj down or isolat$3 or disconnect$3) and shar$3 with terminal$1 and memory	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 10:12	
72	BRS	2	test$3 with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1 or chip$1) and tri-stat$3 with drive$4 and (power$3 or electric$4) with (shut-down or shutdown or shut adj down or isolat$3 or disconnect$3) and shar$3 with terminal$1 and memory	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 10:00	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
73	BRS	0	test$3 with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1 or chip$1) with shar$3 and tri-stat$3 and (power$3 or electric$4) with (shut-down or shutdown or shut adj down or isolat$3 or disconnect$3) and terminal$1 and memory	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 10:01	
74	BRS	20	test$3 with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1 or chip$1) and tri-stat$3 and (power$3 or electric$4) with (shut-down or shutdown or shut adj down or isolat$3 or disconnect$3) and terminal$1 with shar$3 and memory	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 10:01	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
75	BRS	97	test$3 with (IC$1 or integrated adj circuit$1 or wafer$1 or semiconductor$1 or chip$1) and (isolat$3 or tri-stat$3) with driver$1 and electric$4 with (shut-down or shutdown or shut adj down or isolat$3 or disconnect$3) and terminal$1 and memory	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 10:04	
76	BRS	40	"4947357".uref.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 10:08	
77	BRS	5	"4947357".uref. and tri-stat$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 10:08	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
78	BRS	2	test$3 with (IC$1 or integrated adj circuit$1 or wafer$1 or chip$1) with semiconductor$1 and (isolat$3 or tri-stat$3) with drive$4 and (power$3 or electric$4) with (shut-down or shutdown or shut adj down or isolat$3 or disconnect$3) and shar$3 with terminal$1 and memory	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 10:15	
79	BRS	0	test$3 with (IC$1 or integrated adj circuit$1 or wafer$1 or chip$1) with semiconductor$1 and (isolat$3 or tri-stat$3) with connect$3 with shar$3 with terminal$1 and memory and (power$3 or electric$4) with (shut-down or shutdown or shut adj down or isolat$3 or disconnect$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 10:16	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
80	BRS	7	test$3 with (IC$1 or integrated adj circuit$1 or wafer$1 or chip$1) with semiconductor$1 and (isolat$3 or tri-stat$3) with connect$3 and (power$3 or electric$4) with (shut-down or shutdown or shut adj down or isolat$3 or disconnect$3) and shar$3 with terminal$1 and memory	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 10:33	